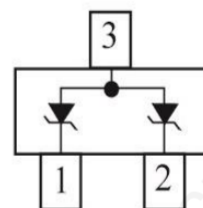
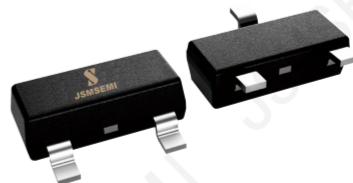


FEATURES

- ◆ We declare that the material of product compliance with RoHS requirements and Halogen Free.
- ◆ S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- ◆ 2 Unidirectional transil functions
- ◆ Low leakage current: $I_R \max < 20 \mu A$ at VRM
- ◆ 260W peak pulse power(8/20 μs)
- ◆ Transient protection for data lines as per IEC61000-4-2 (ESD) 23KV(air) 23KV(contact) IEC61000-4-5(Lightning) see IPPM below



APPLICATIONS

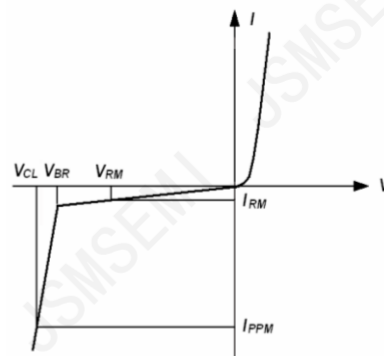
- ◆ Computers
- ◆ Printers
- ◆ Communication systems

ABSOLUTE RATINGS($T_a = 25^\circ C$)

Parameter	Symbol	Limits	Unit
Peak Pulse Power ($t_p = 8/20\mu s$)	PPP	260	W
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	$^\circ C$
Storage Temperature Range	Tstg	$-55 \sim +150$	$^\circ C$
Operating Temperature Range	Top	$-40 \sim +125$	$^\circ C$
Maximum junction temperature	Tj	150	$^\circ C$
Electrostatic discharge IEC61000-4-2 air discharge IEC61000-4-2 contact discharge	VPP	2323	kV

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Symbol	Parameter
VRM	Stand-off voltage
VBR	Breakdown voltage
VCL	Clamping voltage
IRM	Leakage current
IPPM	Peak pulse current

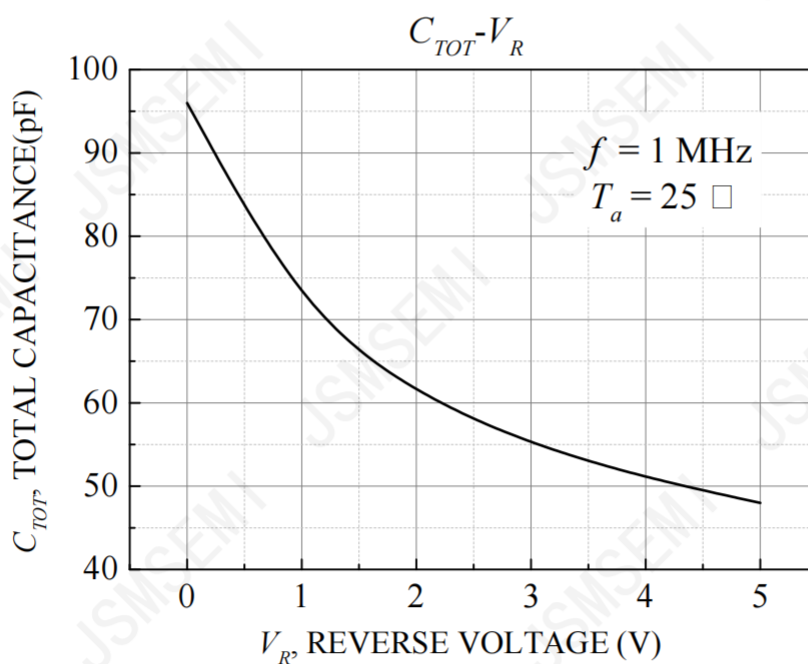
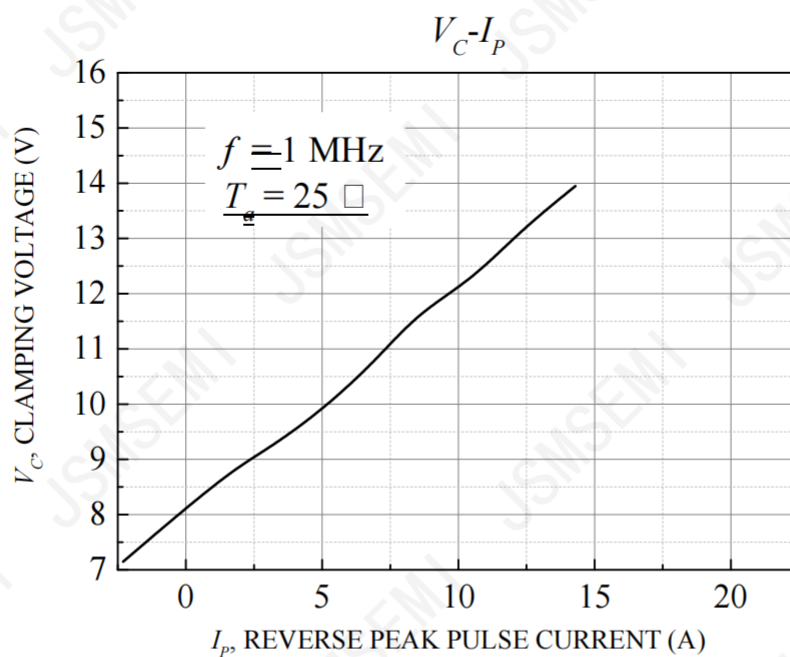


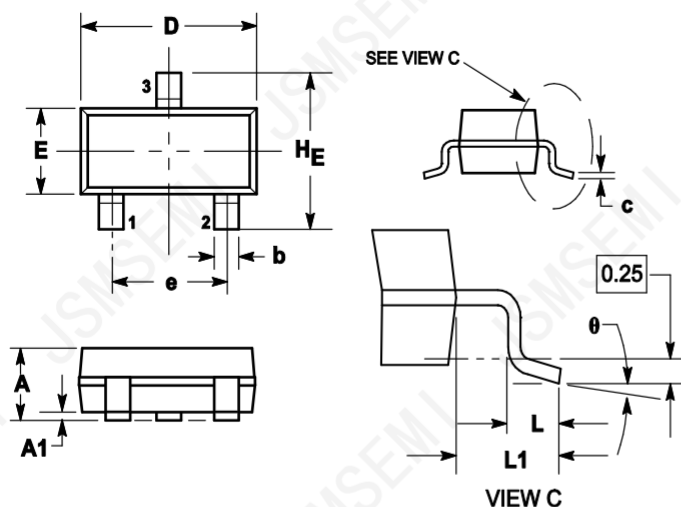
ELECTRICAL CHARACTERISTICS (Ta= 25°C)

DEVICE	VRWM (V)	IR (μA) @VRWM	VBR (V) @IT (Note 1)	IT (mA)	VC (V) @IPP=1A	VC (V) @IPP=13A	IPP(A) @tp=8/20μs	C (pF) f=1MHz
	Max.	Max.	Min.		Max.	Max.	Max.	Max.
PESD5V2S2UT-JSM	5	5	6	1	12	20	13	200

1. 8/20 waveform used.

ELECTRICAL CHARACTERISTICS CURVES



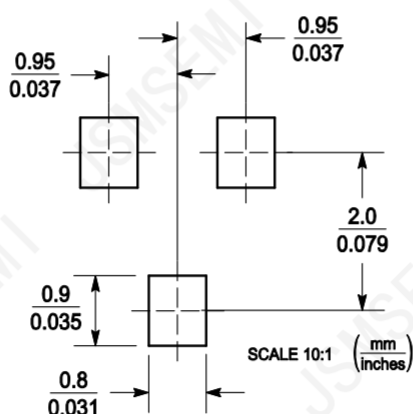


DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H _E	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

SOLDERING FOOTPRINT



Revision History

Rev.	Change	Date
V1.0	Initial version	2/23/2024

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